

PRODUCT CHANGE NOTICE

PCN-2507 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
3 rd Februrary, 2021	3 rd May, 2021	Discrete and Analog Semiconductors	Additional Wafer Backside Material	2507

TITLE

Qualification of Additional Wafer Backside Material Supplier

DESCRIPTION OF CHANGE

This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes subcontractor SJ Semiconductor (SMIC) has qualified LINTEC LC2850 lamination tape as an additional wafer backside material for select products listed in this PCN.

Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached Qualification Report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).

IMPACT

Continuity of Supply. There will be no change to the Form, Fit or Function of products affected.

PRODUCTS AFFECTED

DMP1096UCB4-7	DMN1016UCB6-7
DMP2100UCB9-7	AH1898-CA4-7
DMP1080UCB4-7	AH1892-CD4-7
DMP2540UCB9-7	
DMP2070UCB6-7	
DMN1032UCB4-7	

WEB LINKS			
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/		
For More Information Contact:	http://www.diodes.com/contacts		
Data Sheet:	http://www.diodes.com/products		
DISCLAIMER			

Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.